

**Notice of References Cited**

Application/Control No.

10/636,110

Applicant(s)/Patent Under  
Reexamination  
BALLANTINE ET AL.

Examiner

Tim Phan

Art Unit

3729

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**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,647,614 B1	11-2003	Ballantine et al.	29/610.1
*	B	US-5,310,624	05-1994	Ehrlich, Daniel J.	430/322
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	A Novel Manufacturing Technology of Buried RuO <sub>2</sub> -Based Thick Film Resistors in Copper-Polyimide Substrate, Gofuku et al, 0569-5503/91/0000-0524 @1991 IEEE
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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